

Amendments to the Claims

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-33 (Canceled)

Claim 34 (Currently Amended): A semiconductor device comprising:

a BGA (ball grid array) type semiconductor device including a base plate, a first resin that seals a frontside surface of the base plate, and a plurality of bumps formed on a backside surface of the base plate that is opposite the frontside surface; and

a CSP (chip size packaged) type semiconductor device mounted on an area of the backside surface of the base plate of said BGA type semiconductor device which does not have the plurality of bumps formed thereon,

said CSP type semiconductor device having a semiconductor element which has main and back surfaces, and side surfaces between the main and back surfaces, and a plurality of terminals which are formed on the main surface,

wherein the back surface and the entirety of the side surfaces of the semiconductor element are exposed,

wherein the backside surface of the base plate is mounted to a printed circuit board via the plurality of bumps, and said CSP type semiconductor device as mounted

on the backside surface of the base plate has a thickness less than a thickness of the plurality of bumps, and

wherein said CSP type semiconductor device has a second resin that covers the main surface of the semiconductor element and side surfaces of the terminals, the first and second resins are separate from each other.

Claim 35 (Previously Presented): The semiconductor device of claim 34, wherein the plurality of terminals of said CSP type semiconductor device are electrically connected to the plurality of bumps via wiring patterns formed on the backside surface of the base plate.

Claim 36 (Previously Presented): The semiconductor device of claim 35, wherein the plurality of terminals of said CSP type semiconductor device are coupled to the wiring patterns via solder joints.

Claim 37 (Previously Presented): The semiconductor device of claim 34, wherein said CSP type semiconductor device is mounted on said BGA type semiconductor device so that a front surface of said CSP type semiconductor device faces the backside surface of the base plate.

Claims 38-45 (Canceled)

Claim 46 (Previously Presented): The semiconductor device according to claim 34, wherein the main surface of the semiconductor element faces the backside surface of the base plate.

Claims 47-52 (Canceled):

Claim 53 (Currently Amended): A semiconductor device comprising:

a BGA (ball grid array) type semiconductor device including a base plate, a first resin that seals a frontside surface of the base plate, and a plurality of bumps formed on a backside surface of the base plate that is opposite the frontside surface; and

a CSP (chip size packaged) type semiconductor device mounted on an area of the backside surface of the base plate of said BGA type semiconductor device which does not have the plurality of bumps formed thereon,

said CSP type semiconductor device having a semiconductor element which has main and back surfaces, and side surfaces between the main and back surfaces, and a plurality of terminals which are formed on the main surface,

wherein the back surface and the entirety of the side surfaces of the semiconductor element are exposed,

wherein the main surface of the semiconductor element is sealed with a second resin, and portions of each of the plurality of terminals are exposed from the second resin, the first and second resins are separate from each other, and

wherein the backside surface of the base plate is mounted to a printed circuit board via the plurality of bumps, and said CSP type semiconductor device as mounted on the backside surface of the base plate has a thickness less than a thickness of the plurality of bumps.

Claim 54 (Previously Presented): The semiconductor device according to claim 53, wherein said BGA type semiconductor device has a plurality of conductive portions on the backside surface of the base plate,

the semiconductor device further comprising a plurality of conductive members, each of which is located between a corresponding one of the plurality of conductive portions and the portion of a corresponding one of the plurality of terminals.

Claim 55 (Currently Amended): The semiconductor device according to claim 54, wherein said conductive members are not sealed with the first and second resins said resin.

Claim 56 (Previously Presented): The semiconductor device according to claim 54, wherein said conductive portions are solder.

Claim 57 (Currently Amended): The semiconductor device according to claim 34, wherein said BGA type semiconductor device has a semiconductor element sealed

within the first resin, a size of the semiconductor element of said BGA type semiconductor device is smaller than a size of the semiconductor element of the said CSP type semiconductor device.

Claim 58 (Previously Presented): The semiconductor device according to claim 34, wherein said BGA type semiconductor device and said CSP type semiconductor device are individually manufactured.

Claim 59 (Previously Presented): The semiconductor device of claim 34, wherein said BGA type semiconductor device has a semiconductor element which has a thickness greater than a thickness of the semiconductor element of said CSP type semiconductor device.

Claim 60 (Previously Presented): The semiconductor device according to claim 53, wherein said BGA type semiconductor device has a semiconductor element, a size of the semiconductor element of said BGA type semiconductor device is smaller than a size of the semiconductor element of the said CSP type semiconductor device.

Claim 61 (Currently Amended): The semiconductor device of claim 53, wherein said BGA type semiconductor device has a semiconductor element sealed within the first resin which has a thickness greater than a thickness of the semiconductor element of

said CSP type semiconductor device.